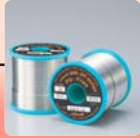


Non-Cu Leaching Products / Post-flux

Minimizes Cu leaching problem with three-metals alloy for various applications. Pb-free compatible liquid flux is also available.

Non-Cu Leaching Product

LFM-41



A core solder which is available for various products, such as SR-34 super and others.

Examples of application :
For thin copper wire soldering by hand.

LFM-59



Using at higher soldering temperature than 400 degrees minimizes Cu leaching phenomenon during soldering.

Examples of application :
For dip soldering, such as coil wire.

LFM-62

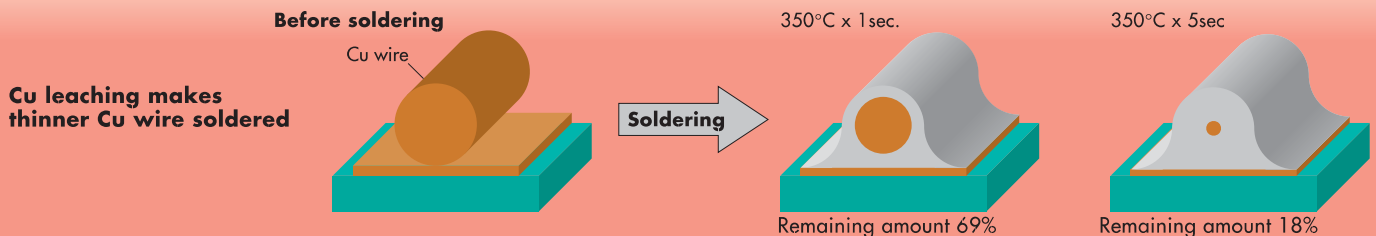


Soldering with extremely fine wire thinner than 50µm. Workable at high soldering temperature over 400°C.

Examples of application :
For dip soldering with extremely fine wire.

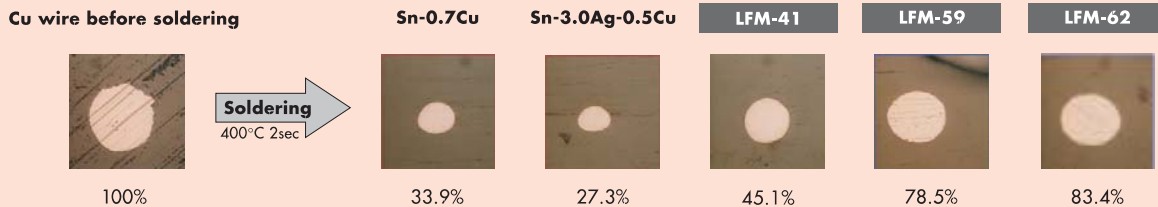
What is [Cu leaching]?

In the case of soldering, parent material's Cu content dissolves into liquid solders making Cu wire thinner. This problem is critical especially for Pb-free soldering. Corrosion amount varies, depending on solder components, soldering temperature, and time.



Difference in remaining amount between other alloys and Cu. (comparison)

[Condition] Dip-solder Cu film wire of 150µm with other alloys for two seconds. Take cross-sectional photos to measure remaining amount of Cu wire. (*Before dip, apply flux.)



Alloy component	Sn-37Pb	Sn-0.7Cu	Sn-3.0Ag-0.5Cu	Sn-3.5Ag-0.7Cu	LFM-41	LFM-59	LFM-62
350°C	63.6	52.2	56	46.6	66.5	--	--
400°C	47.1	33.9	27.3	24.0	45.1	78.5	83.4

*Because LFM-59 and LFM-62 have higher melting point, evaluation was done only at 400°C. (Unit:%)

Non-Cu leaching product specification

Product name	Alloy component	Melting point temperature	Applicable product		
			Core solders	Wire solders (only for 1.00 and 2.00)	Bar solders
LFM-41	Sn-0.3Ag-2.0Cu	217-270°C	○	○	○
LFM-59	Sn-3.0Cu	227-312°C	×	○	○
LFM-62	Sn-3.0Cu-0.5Ni	228-394°C	×	○	○

*LFM-41, a core solder, is available in various types such as SR-34 Super, SR34, KR-19, KR-19SH RMA, HR-19, and GUMMIX-19.

*LFM-59 and LFM-62 contain anti-oxidant. As these fluxes can minimize oxidized residue of solder bus dross during high temperature dip soldering, the consumed amount of flux is reasonably decreased.

*When the ordered product is out of stock, please contact our sales representative for details.

Post-flux

RC-281PF Flux

Highly reliable and desirable countermeasure against bridges, icicles, and insufficient soldering.

Examples of application : Print wiring assembly and special metal soldering.

Post-flux product specification

Product name	Solid content	Relative density	Color tone	Chlorine content
RC-281PF flux	12%	0.815	Light yellow	0

* Please contact our sales representative for details.